

AN 1993-013832 [02] WPIDS
 DNC C1993-006485 [21]
 DNN N1993-010402 [21]
 TI Mfg. copper@ alloy sheets for electronic components - by forming thin
 film of copper@ (alloy) containing tin@, zirconium@, carbon, titanium@ and
 silver@ on copper@ alloy sheet
 DC L03; M13; P73; U11
 IN MANOME M; OZAKI T
 PA (HITD-C) HITACHI CABLE LTD
 CYC 1
 PIA JP 04342159 A 19921127 (199302)* JA 5[3] <--
 ADT JP 04342159 A JP 1991-114627 19910520
 PRAI JP 1991-114627 19910520
 AB JP 04342159 A UPAB: 20050506
 Mfr. comprise forming 0.3-3 micron thick thin film of a Cu(-alloy) containing
 1 atmospheric% or less in total of Sn, Zr, C, Ti and Ag, on at least one side
 of
 a sheet of a Cu alloy containing 1-10 atmospheric% in total of Sn, Zr, C, Ti
 and Ag.
 USE - Exhibits strong adhesion to a different material, and is free
 of smut on pickling.